



micromachines



an Open Access Journal by MDPI

Emerging Smart Materials for Microelectromechanical Systems

Guest Editor:

Dr. Nathan Jackson

Nanoscience and Microsystems
Engineering and Mechanical
Engineering, University of New
Mexico, Albuquerque, NM 87106,
USA

Deadline for manuscript
submissions:

30 June 2024

Message from the Guest Editor

Dear Colleagues,

The development of functional and multifunctional materials for the application of microelectromechanical systems (MEMS) is needed to enhance performance and create new transduction mechanisms for sensors and actuators. Enhancing material properties and developing methods of integrating and fabricating materials is the cornerstone to developing new MEMS devices. Accordingly, this Special Issue seeks to showcase research papers, short communications, and review articles that focus on the development of emerging functional and multifunctional materials for MEMS devices. This includes, but is not limited to, the development of new materials, enhancing material properties, developing new transduction mechanisms for materials, the integration of materials, new deposition techniques, or increasing manufacturing compatibility with MEMS. The Special Issue is interested in all types of functional materials, including 2D and thin films.



mdpi.com/si/192337

Special Issue



Editor-in-Chief

Message from the Editor-in-Chief

You are invited to contribute research articles or comprehensive reviews for consideration and publication in *Micromachines* (ISSN 2072-666X). *Micromachines* is published in the open access format. Research articles, reviews and other contents are released on the internet immediately after acceptance. The scientific community and the general public have unlimited free access to the content as soon as it is published. As an open access journal, *Micromachines* is supported by the authors or their institutes by payment of article processing charges (APC) for accepted papers. We are pleased to welcome you as our authors.

Author Benefits

Open Access: free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility: indexed within Scopus, SCIE (Web of Science), PubMed, PMC, Ei Compendex, dblp, and other databases.

Journal Rank: JCR - Q2 (*Chemistry, Analytical*) / CiteScore - Q2 (*Mechanical Engineering*)

Contact Us

Micromachines Editorial Office
MDPI, St. Alban-Anlage 66
4052 Basel, Switzerland

Tel: +41 61 683 77 34
www.mdpi.com

mdpi.com/journal/micromachines
micromachines@mdpi.com
[X@micromach_mdpi](https://x.com/micromach_mdpi)